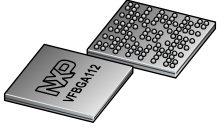


SOT2137-1

VFPGA112; very thin fine-pitch ball grid array, 112 terminals, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body

10 September 2024

Package information



1 Package summary

Package type descriptive code	VFPGA112
Package style descriptive code	VFPGA (very thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	07-04-2023
Manufacturer package code	98ASA02081D

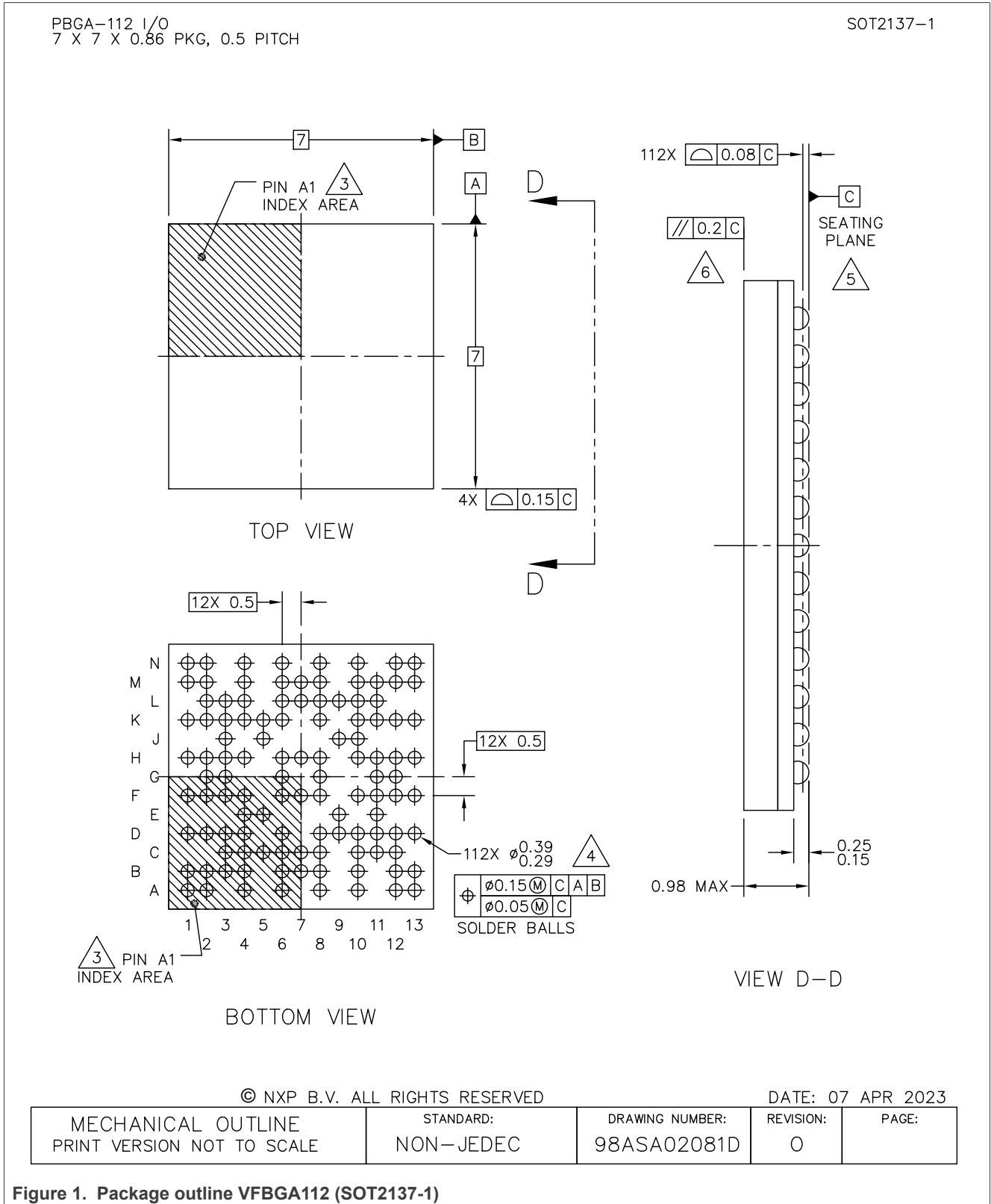
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	6.85	7	7.15	mm
package width	6.85	7	7.15	mm
package height	0.74	0.86	0.98	mm
package diameter	0.29	0.38	0.39	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	112	-	



VFBGA112; very thin fine-pitch ball grid array, 112 terminals, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body

2 Package outline



VFBGA112; very thin fine-pitch ball grid array, 112 terminals, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body

3 Soldering

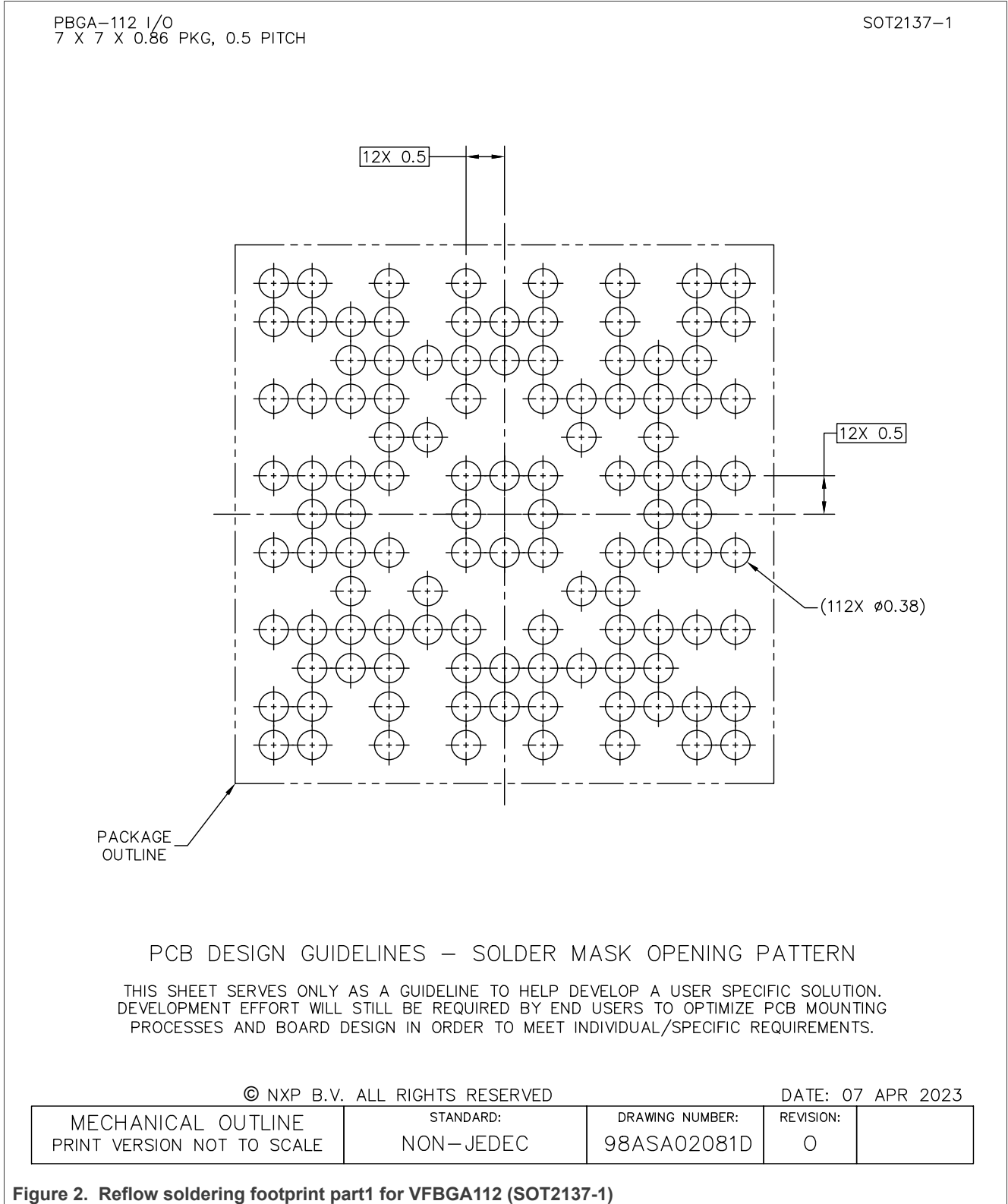
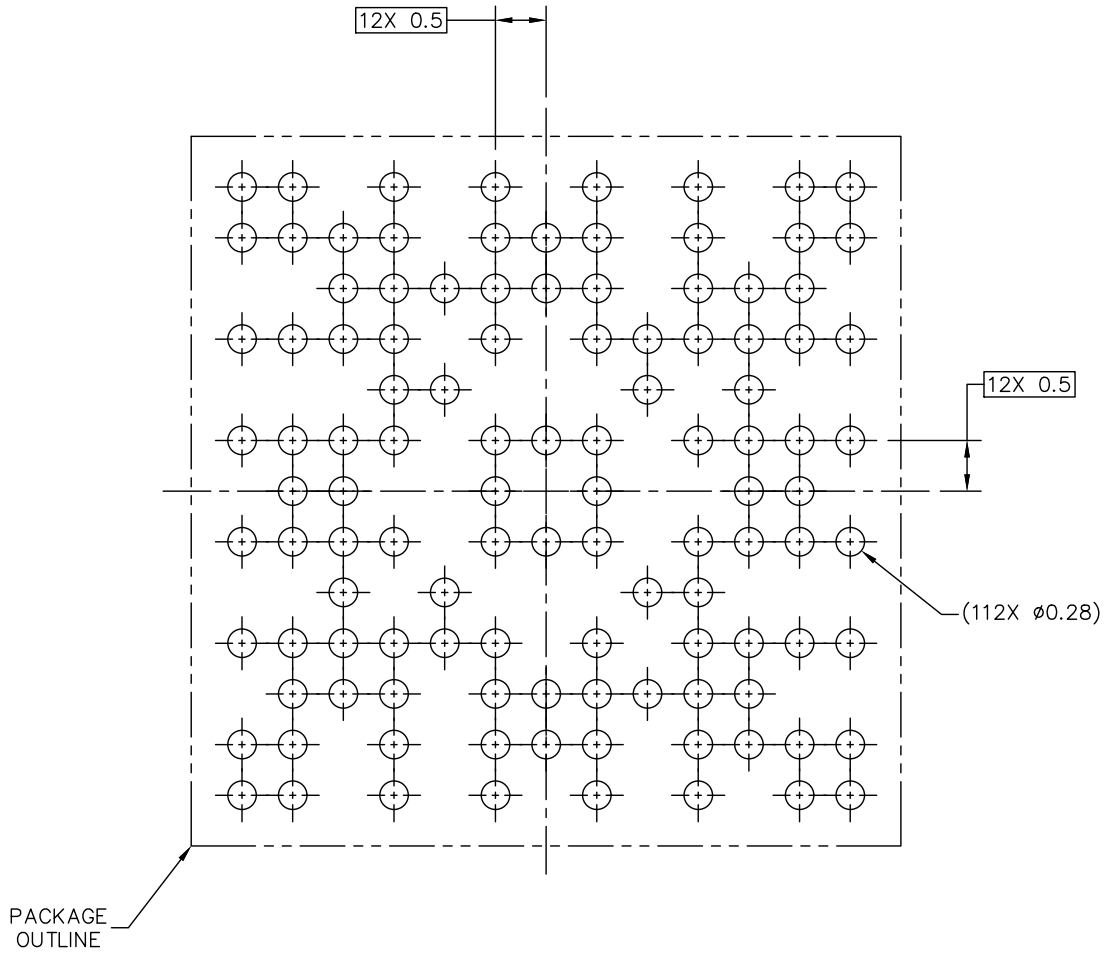


Figure 2. Reflow soldering footprint part1 for VFBGA112 (SOT2137-1)

VFBGA112; very thin fine-pitch ball grid array, 112 terminals, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body

PBGA-112 I/O
7 X 7 X 0.86 PKG, 0.5 PITCH

SOT2137-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 07 APR 2023

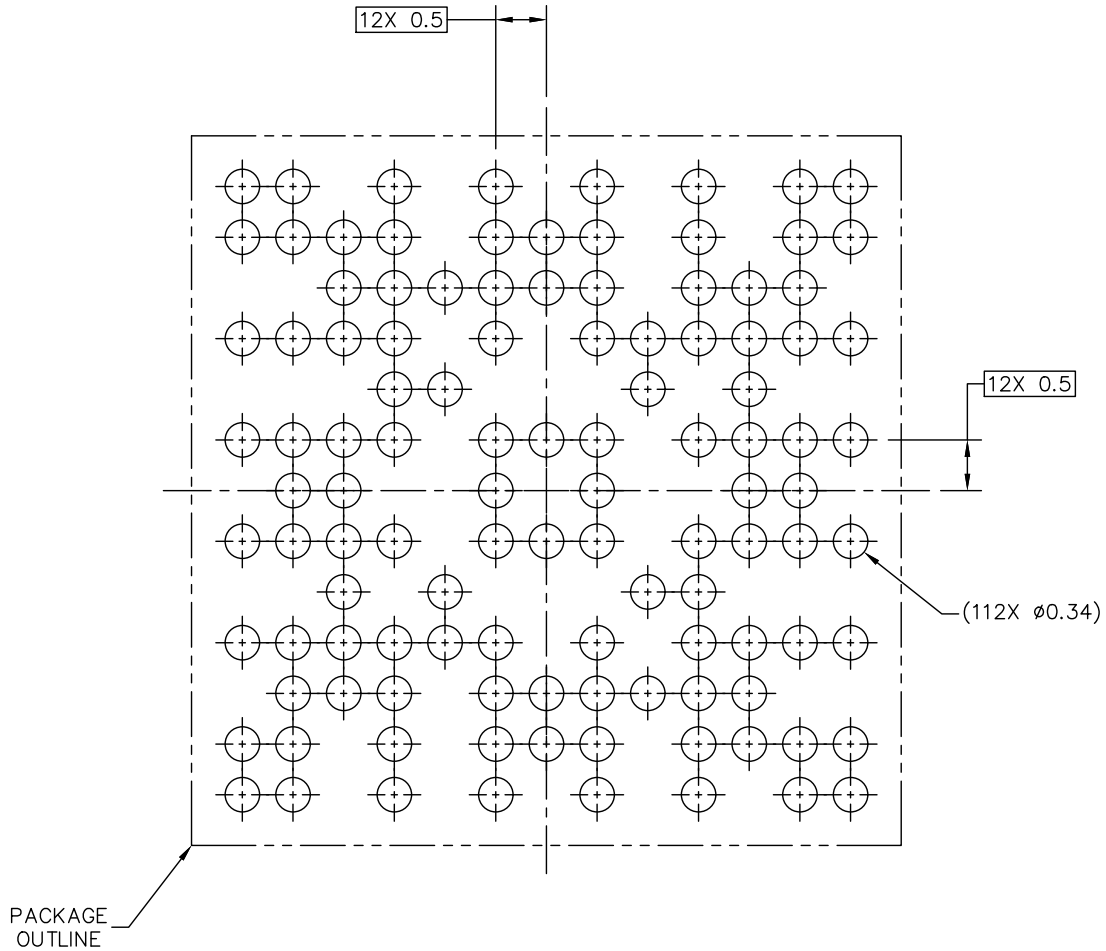
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA02081D	REVISION: 0	
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Figure 3. Reflow soldering footprint part2 for VFBGA112 (SOT2137-1)

VFBGA112; very thin fine-pitch ball grid array, 112 terminals, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body

PBGA-112 I/O
7 X 7 X 0.86 PKG, 0.5 PITCH

SOT2137-1



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for VFBGA112 (SOT2137-1)

VFBGA112; very thin fine-pitch ball grid array, 112 terminals, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body

PBGA-112 I/O
7 X 7 X 0.86 PKG, 0.5 PITCH

SOT2137-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 07 APR 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA02081D	REVISION: 0	
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Figure 5. Package outline note VFBGA112 (SOT2137-1)

VFBGA112; very thin fine-pitch ball grid array, 112 terminals, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm
body

4 Legal information

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VFBGA112; very thin fine-pitch ball grid array, 112 terminals, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body

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